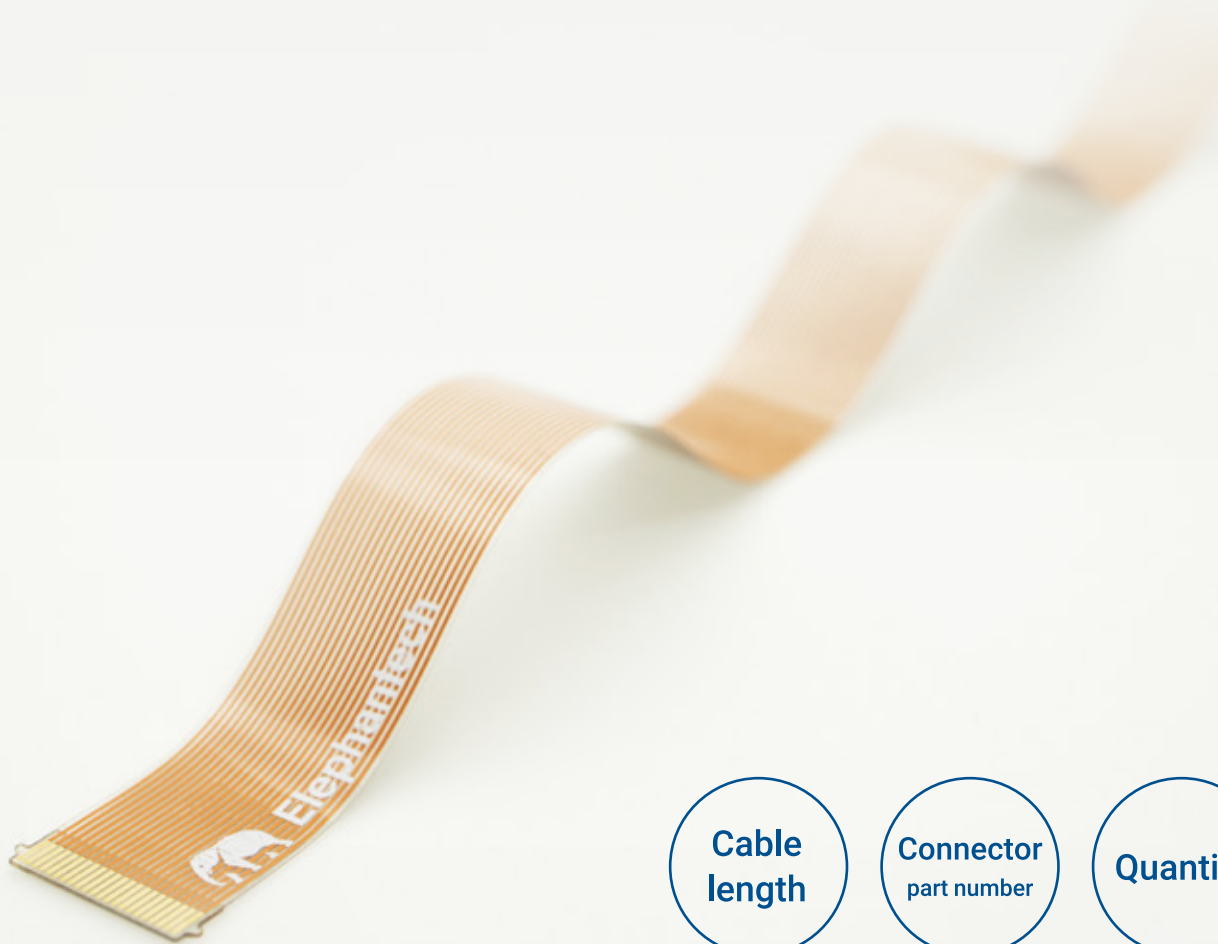




Elephantech

P-Flex[®] PET Applications

Custom single-sided flexible flat cable



Cable
length

Connector
part number

Quantity

Provide estimate with above information

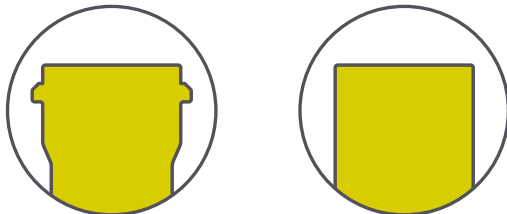
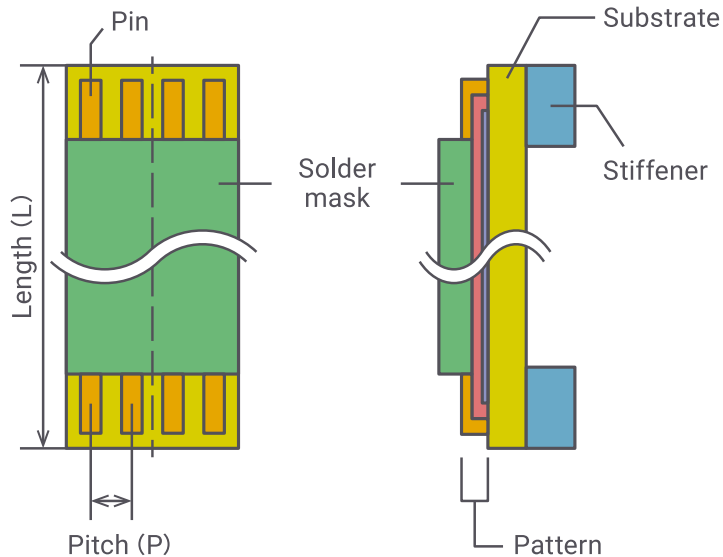
Merits

With inkjet patterning / photo mask and mold less manufacturing, various custom requests are acceptable. We can make cables of any shape and pin count according to your request regardless of quantity.

- ✓ Quick delivery by photomask and mold less manufacturing
- ✓ Supports pitch conversion cables such as 0.5 mm ↔ 0.4 mm
- ✓ Complex connector shapes such as with ears are available
- ✓ Custom L or S shaped cuttings are also available as an option

Please contact us using the contact information on the back

Basic Specifications for Custom single-sided flexible flat cable



Examples of connector shapes

Main specifications

Available pin count	4 pins ~ 100 pins
Available pitch	0.4 (Special specifications), 0.5, 0.8, 1.0, 1.25 (mm)
Cable length	30 ~ 260 (mm)
Exposed contacts	Same side
Copper foil thickness	3 μ m, 6 μ m (Special specifications)
Terminal finish	Electroless Ni-Au plating
Stiffener material	PET, Polyimide
Total thickness of the connector connection	0.2, 0.3 mm approximately
Substrate	PET 50 μ m, 125 μ m, Polyimide 25 μ m

*Please note that 0.3mm pitch connectors are not yet available. Also, we may not be able to comply with demands depending on the connector shape.

Compatible connectors

Manufacturer name: HIROSE, Molex, Panasonic, JST (Japanese Solderless Terminals Co., Ltd.) and others.
Please contact us for details such as part numbers.

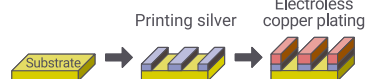
About P-Flex[®]

About Elephantech's manufacturing method (Pure Additive[™] processing)

This manufacturing method consists of inkjet-printing silver nano-ink onto the substrate before electroless copper plating is applied to form the circuit. By reducing the amount of metal, liquid waste and man-hours, we can lessen manufacturing costs and shorten the lead time.

(* Patent No. 6300213 acquired)

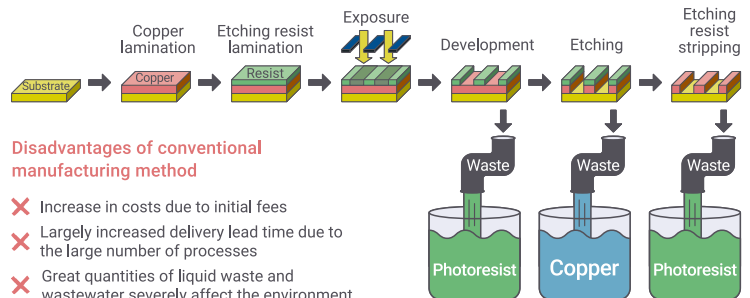
Elephantech's manufacturing method (Pure Additive[™] processing)



Advantages of Elephantech's manufacturing method

- ✓ Forming the circuit only where needed allows for a reduction in manufacturing cost and environmental footprint.
- ✓ A simple manufacturing process allowing for a shorter lead time.

Conventional manufacturing method (subtractive method)



Disadvantages of conventional manufacturing method

- ✗ Increase in costs due to initial fees
- ✗ Largely increased delivery lead time due to the large number of processes
- ✗ Great quantities of liquid waste and wastewater severely affect the environment

P-Flex[®] manufacturing specifications

Substrate	Transparent heat-resistant PET film: 50 μ m thick, 125 μ m thick PI (Polyimide) film: 25 μ m thick
Line width / spacing	200/200 μ m min. 200/150 μ m min. (only PET substrate option)
Outline-pattern spacing	0.3 mm min.
Operating temperature	Between -20 °C and +105 °C
Copper foil thickness	3 μ m (contact us for thicker options)
Panel size	180 × 270 mm max.
Wiring layer	Single-sided
Soldermask coating (PET)	UV inkjet printing (transparent)
Coverlay pasting (PI)	PI film 12.5 μ m, adhesion layer 15 μ m
Legend printing	UV inkjet printing (white)
Surface finish	Oxidation prevention treatment, Electroless Ni-Au plating (option)
Outline cutting / Hole drilling	Laser cutting
Stiffeners	Wide range of material and thickness
PCBA Service	Available. Subject to negotiation.

Company Overview



Elephantech

Elephantech Inc.
(Formerly AgIC Inc.*)

*Changed corporate name on September 4, 2017

Website



Contact



Establishment	January 6, 2014
Address	4-3-8 Hatchobori, Chuo-ku, Tokyo 104-0032, Japan
Capital	JPY 310 million
Representative	Shinya Shimizu, CEO
Website	https://www.elephantech.co.jp/en/
Contact	https://www.elephantech.co.jp/en/about/#contact